

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A heat-dissipating member,
which comprises a thermoplastic resin composition
containing a thermoplastic resin and a thermally conductive fine
particle and not containing a compound having a melting
temperature in the range of 40 to 80°C,

at 23°C, a storage modulus at 0.1 Hz being 50,000 Pa or
larger and the member remains finite in shape, and

in the range of 50 to 80°C, a storage modulus at 0.1 Hz
being 400 to 50,000 Pa and the member being indefinite in shape,
and

at 100°C, a storage modulus at 0.1 Hz being 5,000 Pa or
smaller and the member being indefinite in shape.

2. (original): The heat-dissipating member according to
claim 1,

wherein the thermoplastic resin is a styrene block
copolymer and/or a butyl-rubber resin.

3. (original): The heat-dissipating member according to
claim 2,

wherein the styrene block copolymer is a styrene-isoprene-
styrene block copolymer having the proportion of diblock of
styrene-isoprene being 50% by weight or larger and the content
of styrene being 25% by weight or smaller.

4. (currently amended): The heat-dissipating member according to claim 1, ~~2-or-3,~~

wherein the thermoplastic resin composition mainly contains an aromatic thermoplastic resin being solid at 23°C and further contains a xylene resin having viscosity at 23°C.

5. (currently amended): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 1, ~~2, 3-or-4,~~

wherein thickness of the heat-dissipating member may be reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

6. (currently amended): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 1, ~~2, 3-or-4,~~

wherein thickness of the heat-dissipating member has already been reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

7. (new): The heat-dissipating member according to claim 2, wherein the thermoplastic resin composition mainly contains an aromatic thermoplastic resin being solid at 23°C and further contains a xylene resin having viscosity at 23°C.

8. (new): The heat-dissipating member according to claim 3,

wherein the thermoplastic resin composition mainly contains an aromatic thermoplastic resin being solid at 23°C and further contains a xylene resin having viscosity at 23°C.

9. (new): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 2,

wherein thickness of the heat-dissipating member may be reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

10. (new): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 3,

wherein thickness of the heat-dissipating member may be reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

11. (new): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 4,

wherein thickness of the heat-dissipating member may be reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

12. (new): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 2,

wherein thickness of the heat-dissipating member has already been reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

13. (new): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 3,

wherein thickness of the heat-dissipating member has already been reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.

14. (new): A joined structure obtainable by joining a heat sink to a heat generating element with the heat-dissipating member according to claim 4,

wherein thickness of the heat-dissipating member has already been reduced by heat generation of the heat generating element compared with thickness of the member before the heat generation.